

PRODUCT SPECIFICATION

5.0" TFT LCD MODULE MODEL: YDP LCD I R 500 MI



< ◇ > Preliminary Specification

< ◆ > Finally Specification

CUSTOMER'S APPROVAL	
CUSTOMER :	
SIGNATURE:	DATE:

APPROVED BY	PM REVIEWED	PD REVIEWED	PREPARED BY
TFT S. G. H 20221019			TFT L. Q 20221019

knitter-switch

Revision History

Revision	Date	Originator	Detail	Remarks
1.0	2019.07.08	ZDT	Initial Release	
1.1	2019.08.28	ZDT	Modify Outline Drawing	P25
1.2	2022.10.19	LQ	Add Weight Add Current Consumption Add CIE Value	P4 P5 P6

Table of Contents

No.	Item	Page
1.	General Description	4
2.	Module Parameter	4
3.	Absolute Maximum Ratings	4
4.	DC Characteristics	5
5.	Backlight Characteristic	5
5.1.	Backlight Characteristic	5
5.2.	Backlight Characteristic	5
6.	Optical Characteristics	6
6.1.	Optical Characteristics	6
6.2.	Definition of Response Time	6
6.3.	Definition of Contrast Ratio	7
6.4.	Definition of Viewing Angles	7
6.5.	Definition of Color Appearance	8
6.6.	Definition of Surface Luminance, Uniformity and Transmittance	8
7.	Block Diagram and Power Supply	9
8.	Interface Pins Definition	10
9.	SIGNAL TIMING SPECIFICATION	12
9.1.	Vertical Timings	12
9.2.	Horizontal Timings	13
10.	Reset input timing	14
11.	Quality Assurance	15
11.1.	Purpose	15
11.2.	Standard for Quality Test	15
11.3.	Nonconforming Analysis & Disposition	15
11.4.	Agreement Items	15
11.5.	Standard of the Product Visual Inspection	15
11.6.	Inspection Specification	16
11.7.	Classification of Defects	20
11.8.	Identification/marketing criteria	20
11.9.	Packing	20
12.	Reliability Specifi cation	21
13.	Precautions and Warranty	22
13.1.	Safety	22
13.2.	Handling	22
13.3.	Storage	22
13.4.	Metal Pin (Apply to Products with Metal Pins)	22
13.5.	Operation	23
13.6.	Static Electricity	23
13.7.	Limited Warranty	23
14.	Packaging	24
15.	Outline Drawing	25

1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver Ics and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	5.0"	
LCD type	IPS TFT	
Display Mode	Transmissive /Normally black	
Resolution	1080 RGB x 1080	Pixels
View Direction	FULL VIEW	Best Image
Module Outline	132.208(H) x 136.531 (V) x 1.98 (T) (Note1)	mm
Active Area	127.008 (H) x 127.008 (V)	mm
Pixel Size	117.6 (H) x 117.6 (V)	um
Pixel Arrangement	1pixel 2domain	
Display Colors	16.7M	
Interface	MIPI interface	
With or without touch panel	Without	
Driver IC	HX8399C	-
Operating Temperature	-20~60	°C
Storage Temperature	-30~70	°C
Weight	70	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

GND=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	IOVCC	-0.3	3.6	V
Analog Positive Power Supply	VSP	-0.3	6.6	V
Analog Negative Power Supply	VSN	0	-6.6	V
Storage temperature	T _{STG}	-30	+70	°C
Operating temperature	T _{OP}	-20	+60	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	IOVCC	1.65	1.8	3.3	V
Analog Positive Power Supply	VSP	4.8	5	6	V
Analog Negative Power Supply	VSN	-6	-5	-4.8	V
VDDIO Input low level voltage	V _{IL}	0	-	0.3*IOVCC	mV
VDDIO Input high level voltage	V _{IH}	0.7*IOVCC	-	IOVCC	mV
Current Consumption All white	Logic	-	20	-	mA
	Analog				
I _{CC}					

5. Backlight Characteristic

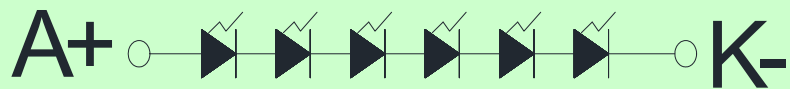
5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	Ta=25 °C, I _F =20mA/LED	-	37.2	38.4	V
Forward Current	I _F	Ta=25 °C, V _F =6.2V/LED	-	20	-	mA
Power dissipation	P _D		-	744	-	mW
Uniformity	Avg		70	-	-	%
Drive method	Constant current					
LED Configuration	6 White LEDs (6 LEDs in one string)					

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25±2 °C, 60%RH±5%, I_F=20mA/LED.

5.2. Backlight Characteristic



6. Optical Characteristics

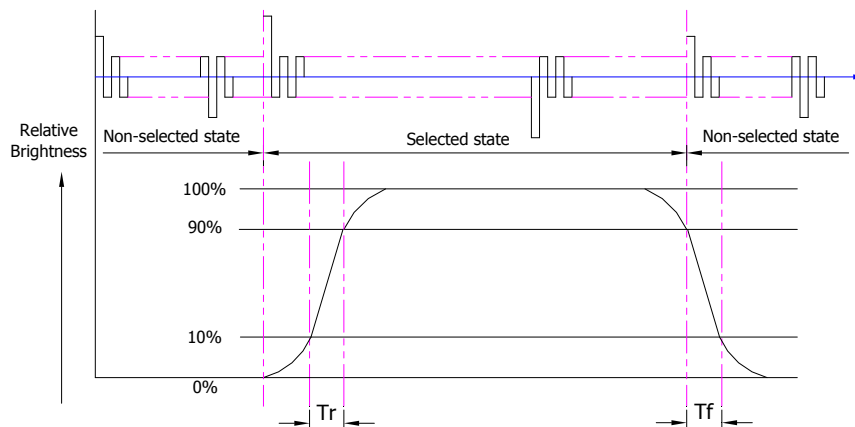
6.1. Optical Characteristics

Ta=25°C, IOVCC=1.8V

Backlight On (Transmissive Mode)	Item		Symbol	Condition	Specification			Unit
					Min.	Typ.	Max.	
	Luminance on TFT(I_f =20mA/LED)		Lv	Normally viewing angle $\theta_x = \varphi_y = 0^\circ$	320	400	-	cd/m ²
	Contrast ratio(See 6.3)		CR		800	1300	-	
	Response time (See 6.2)		T _R +T _F		-	-	40	Ms
	Chromaticity Transmissive (See 6.5)	Red	X _R		0.615	0.665	0.715	
			Y _R		0.268	0.318	0.368	
		Green	X _G		0.243	0.293	0.343	
			Y _G		0.557	0.607	0.657	
		Blue	X _B		0.082	0.132	0.182	
			Y _B		0.006	0.056	0.106	
		White	X _W		0.233	0.283	0.333	
			Y _W		0.274	0.324	0.374	
	Viewing Angle (See 6.4)	Horizontal	θ _x +	Center CR≥10	70	80	-	Deg.
			θ _x -		70	80	-	
Vertical		φ _y +	70		80	-		
		φ _y -	70		80	-		
NTSC Ratio(Gamut)				65	70	-	%	

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

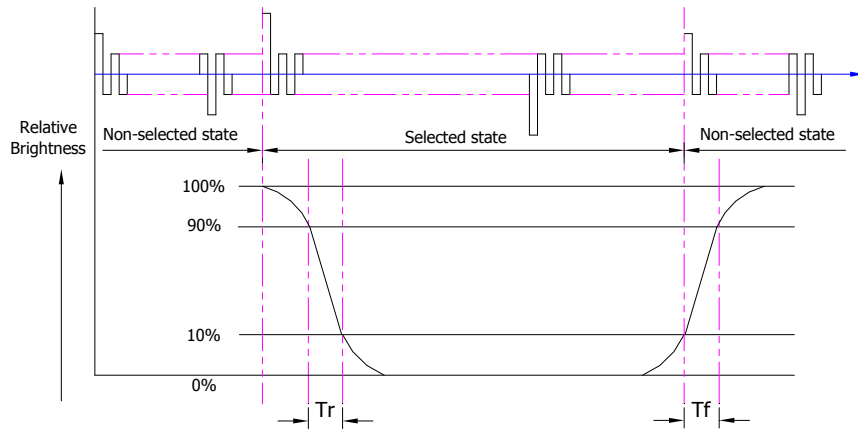


T_r is the time it takes to change from non-selected state with relative luminance 10% to selected state with relative luminance 90%;

T_f is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



T_r is the time it takes to change from non-selected state with relative luminance 90% to selected state with relative luminance 10%;

T_f is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

6.3. Definition of Contrast Ratio

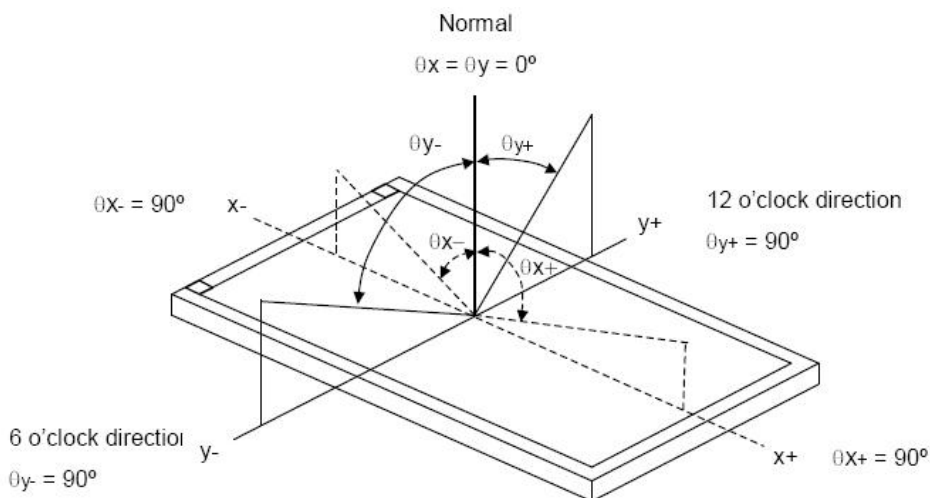
Contrast is measured perpendicular to display surface in reflective and transmissive mode.

The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test pattern	A: All Pixels white
	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



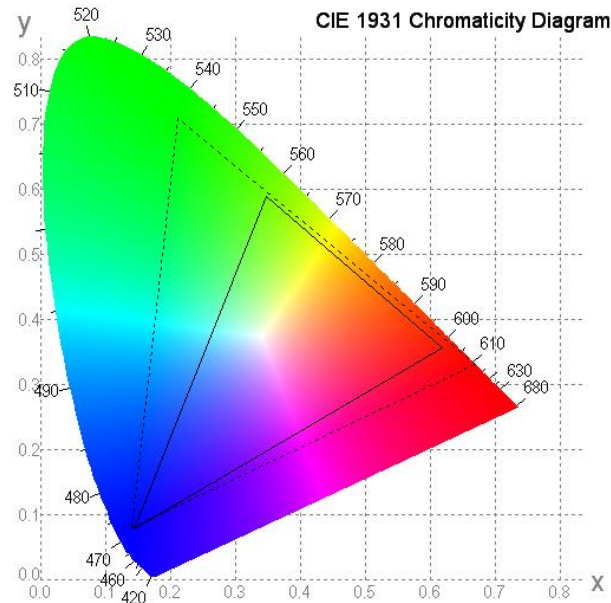
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

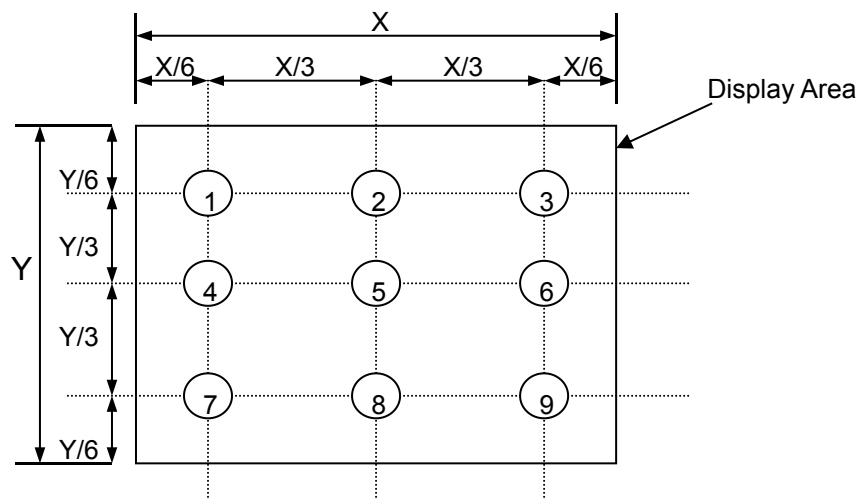
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.6.1. Surface Luminance: $L_V = \text{average } (L_{P1}:L_{P9})$

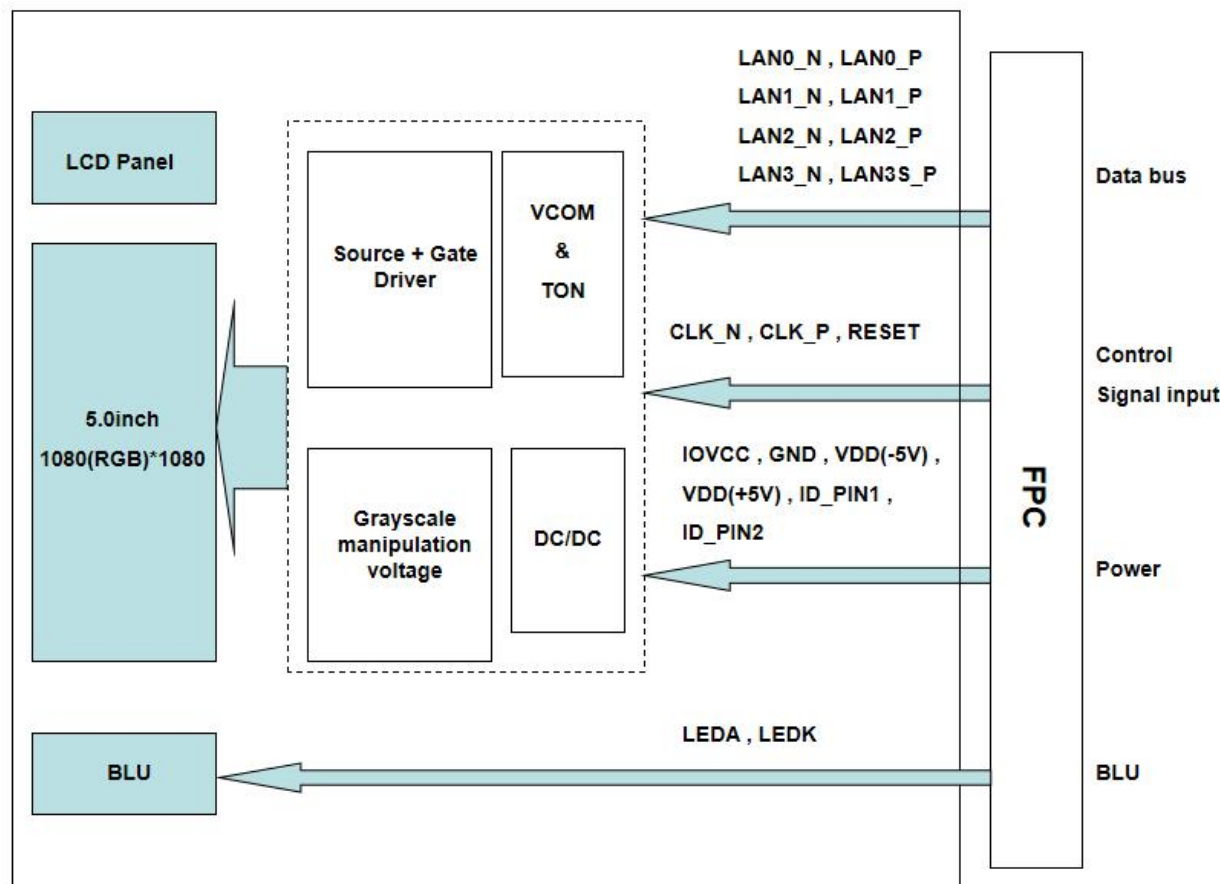
6.6.2. Uniformity = $\text{Minimal } (L_{P1}:L_{P9}) / \text{Maximal } (L_{P1}:L_{P9}) * 100\%$

6.6.3. Transmittance = $L_V \text{ on LCD} / L_V \text{ on Backlight} * 100\%$

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply



8. Interface Pins Definition

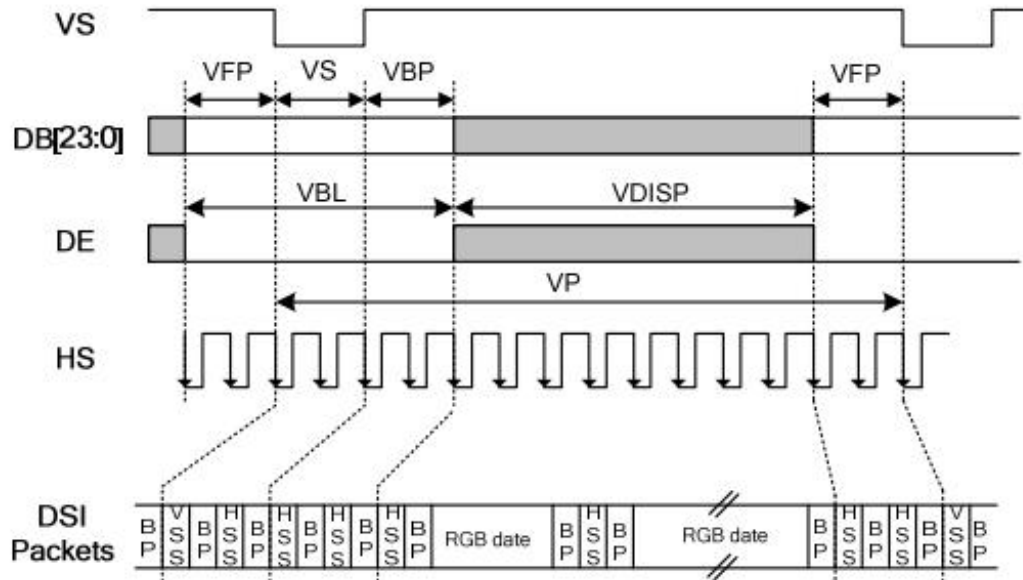
Connector: DF40C-50DP-0.4V

No.	Symbol	Function	Remark
1	GND	Ground	
2	GND	Ground	
3	LAN2_P	Disp MIPI lane 2+	
4	LEDK	LED cathode	
5	LAN2_N	Disp MIPI lane 2-	
6	LEDK	LED cathode	
7	GND	Ground	
8	GND	Ground	
9	LAN1_P	Disp MIPI lane 1+	
10	LEDA	LED Anode	
11	LAN1_N	Disp MIPI lane 1-	
12	LEDA	LED Anode	
13	GND	Ground	
14	GND	Ground	
15	CLK_P	Disp MIPI CLK+	
16	ID_PIN2	ID pd to 1.8V (BOE)	
17	CLK_N	Disp MIPI CLK-	
18	ID_PIN1	ID pd to GND (BOE)	
19	GND	Ground	
20	GND	Ground	
21	LAN0_P	Disp MIPI lane 0+	
22	IOVCC	Disp digital power	
23	LAN0_N	Disp MIPI lane 0-	
24	IOVCC	Disp digital power	
25	GND	Ground	
26	GND	Ground	
27	LAN3_P	Disp MIPI lane 3+	
28	NC	No connection	
29	LAN3_N	Disp MIPI lane 3-	
30	VDD(-5V)	Display -5V analog rail	
31	GND	Ground	
32	VDD(-5V)	Display -5V analog rail	
33	NC	No connection	
34	NC	No connection	
35	NC	No connection	
36	VDD(+5V)	Display +5V analog rail	
37	GND	Ground	
38	VDD(+5V)	Display +5V analog rail	
39	NC	No connection	

40	NC	No connection	
41	NC	No connection	
42	GND	Ground	
43	NC	No connection	
44	LEDPWM	Backlight pwm output	
45	NC	No connection	
46	TE	Disp tearing effect out	
47	GND	Ground	
48	RESET	Disp reset	
49	GND	Ground	
50	GND	Ground	

9. SIGNAL TIMING SPECIFICATION

9.1. Vertical Timings

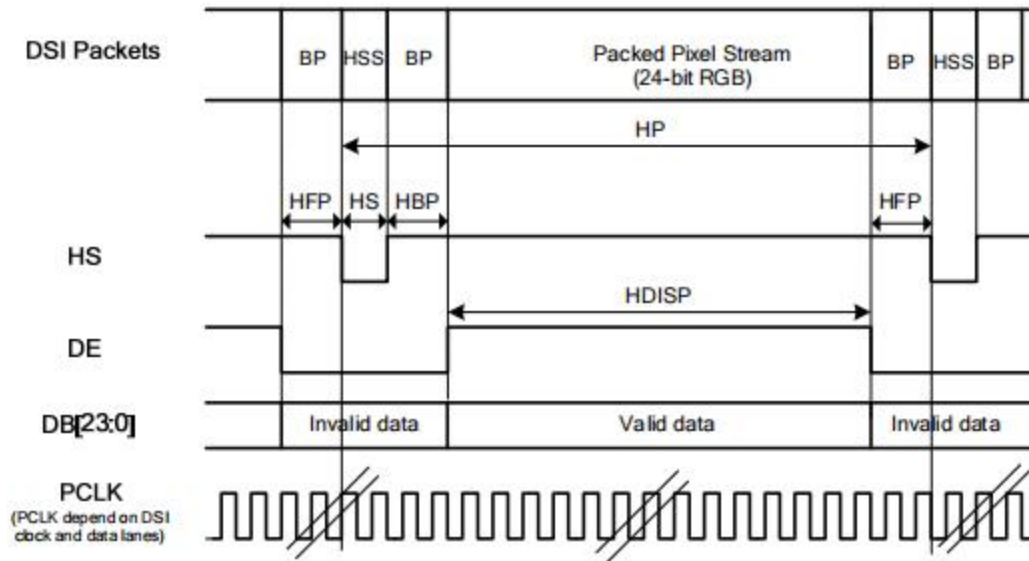


Vertical Resolution=528+8xNL (VSSA=0V, VDD1=1.8V, VDD3=2.8V, T_A=25°C)

Parameter	Symbol	Condition	Spec.			Unit
			Min.	Typ.	Max.	
Vertical cycle	VP	-	534+8xNL	-	-	Line
Vertical low pulse width	VS	-	2	-	Note ⁽¹⁾	Line
Vertical front porch	VFP	-	2	-	-	Line
Vertical back porch	VBP	-	2	-	Note ⁽¹⁾	Line
Vertical data start point	-	VS+VBP	4	-	Note ⁽¹⁾	Line
Vertical blanking period	VBL	VS+VBP+VFP	6	-	-	Line
Vertical active area	-	VDISP	-	528+8xNL	-	Line
Vertical Refresh rate	VRR	-	-	60	-	Hz

Note: (1) The VS and VBP pulse width are related to GSP and GCK timing. The GSP and GCK must be set at corresponding position for LCD normal display.

9.2. Horizontal Timings

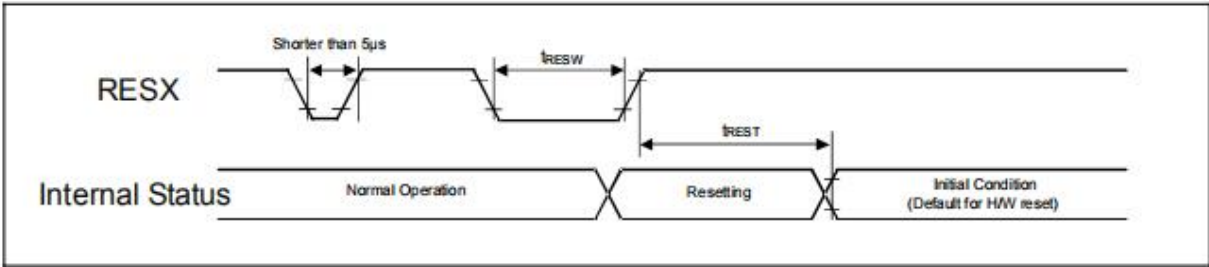


Horizontal Resolution=H_RES(1080/1024/960/900/800/720) (VSSA=0V, VDD1=1.8V, VDD3 = HS_VCC =2.8V, T_A=25°C)

Parameter	Symbol	Condition	Spec.			Unit
			Min.	Typ.	Max.	
HS cycle	HP	-	H_RES+66	-	-	DCK
HS low pulse width	HS	-	25	-	-	DCK
Horizontal back porch	HBP	-	25	-	-	DCK
Horizontal front porch	HFP	-	16	-	-	DCK
Horizontal data start point	-	HS+HBP	50 Note ⁽¹⁾	-	-	DCK
Horizontal blanking period	HBLK	HS+HBP+HFP	66	-	-	DCK
Horizontal active area	HDISP	-	-	H_RES	-	DCK

Note: (1) HS+HBP must larger than 50 PCLK.

10. Reset input timing

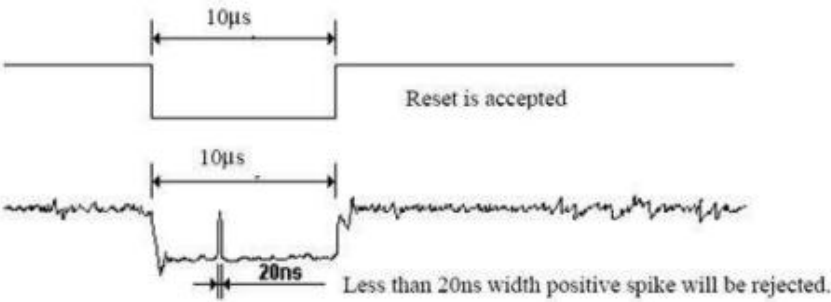


Symbol	Parameter	Related pins	Spec.			Unit	Note
			Min.	Typ.	Max.		
t_{RESW}	Reset low pulse width ⁽¹⁾	RESX	10	-	-	µs	-
t_{REST}	Reset complete time ⁽²⁾	-	-	-	50	ms	-

Note: (1) Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below.

RESX Pulse	Action
Shorter than 5µs	Reset Rejected
Longer than 10µs	Reset
Between 5µs and 10µs	Reset Start

- (2) During Reset Complete Time, OTP will be latched to internal register during this period. This loading is done every time when there is H/W reset complete time (t_{REST}) within 5ms after a rising edge of RESX.
(3) Spike Rejection also applies during a valid reset pulse as shown below:



11. Quality Assurance

11.1. Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

11.2. Standard for Quality Test

11.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

11.2.2. Sampling Criteria:

Visual inspection: AQL 1.5.

Electrical functional: AQL 0.65.

11.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

11.3. Nonconforming Analysis & Disposition

11.3.1. Nonconforming analysis:

11.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.

11.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

11.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.

11.3.2. Disposition of nonconforming:

11.3.2.1. Non-conforming product over PPM level will be replaced.

11.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

11.4. Agreement Items

Shall negotiate with customer if the following situation occurs:

11.4.1. There is any discrepancy in standard of quality assurance.

11.4.2. Additional requirement to be added in product specification.

11.4.3. Any other special problem.

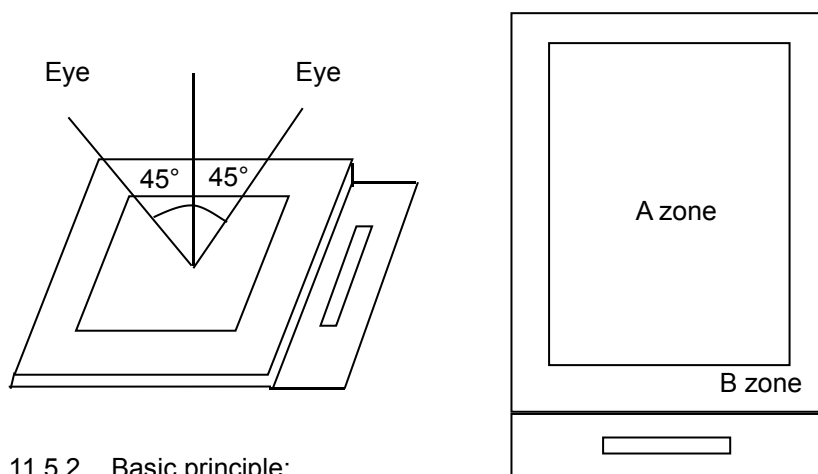
11.5. Standard of the Product Visual Inspection

11.5.1. Appearance inspection:

11.5.1.1. The inspection must be under illumination about 1000 – 1500 lx, and the distance of view must be at 30cm $\pm$ 2cm.

11.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

11.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,

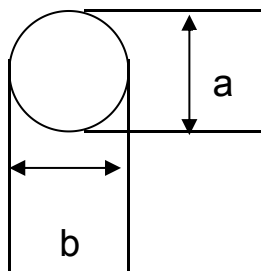


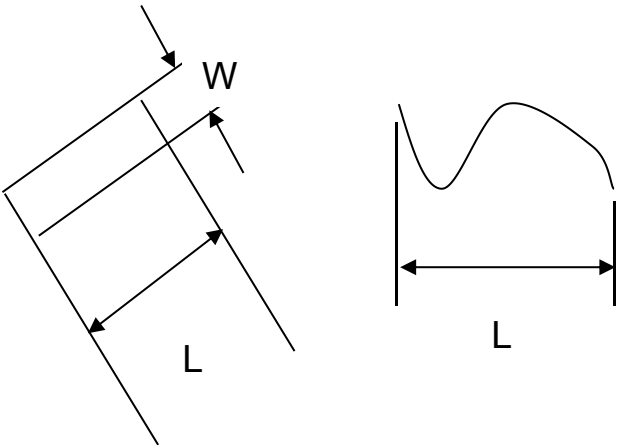
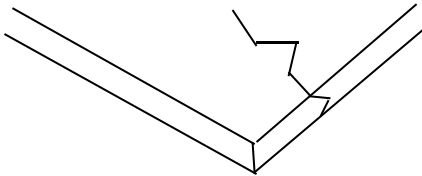
11.5.2. Basic principle:

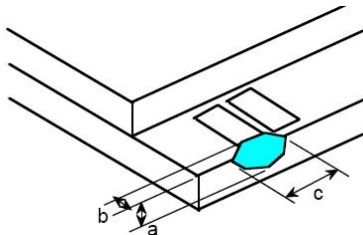
11.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

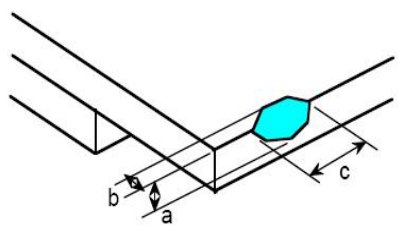
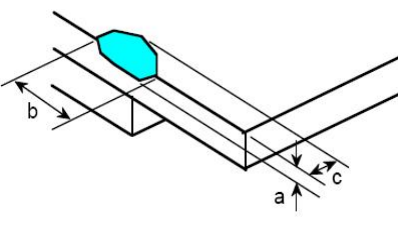
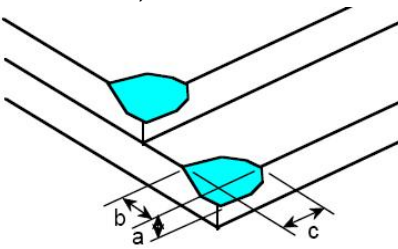
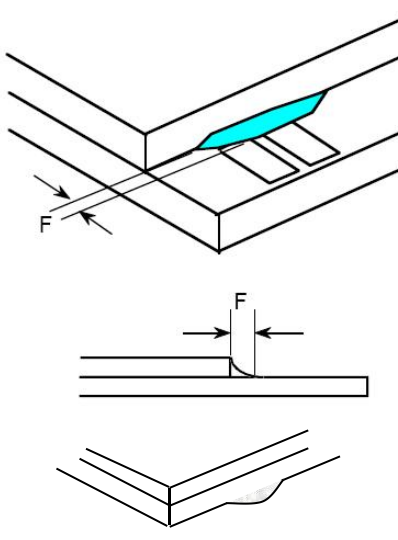
11.5.2.2. New item must be added on time when it is necessary.

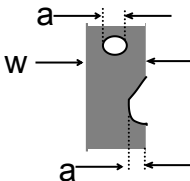
11.6. Inspection Specification

No.	Item	Criteria (Unit: mm)																		
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	 $\phi = (a + b) / 2$ Distance between 2 defects should more than 3mm apart.	<table><tr><th>Size \ Area</th><th>Acc. Qty</th></tr><tr><td>$\phi \leq 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < \phi \leq 0.50$</td><td>$N \leq 3$</td></tr><tr><td>$0.50 < \phi$</td><td>0</td></tr></table>	Size \ Area	Acc. Qty	$\phi \leq 0.20$	Ignore	$0.20 < \phi \leq 0.50$	$N \leq 3$	$0.50 < \phi$	0									
			Size \ Area	Acc. Qty																
$\phi \leq 0.20$	Ignore																			
$0.20 < \phi \leq 0.50$	$N \leq 3$																			
$0.50 < \phi$	0																			
02	Electrical Defect (Minor defect)	<table><tr><td></td><td>Display Area</td><td>Total</td><td rowspan="3">Note 1</td></tr><tr><td>Bright dot</td><td>$N \leq 2$</td><td>$N \leq 2$</td></tr><tr><td>Dark dot</td><td>$N \leq 4$</td><td>$N \leq 4$</td></tr><tr><td>Total dot</td><td>$N \leq 4$</td><td>$N \leq 4$</td><td rowspan="2">Note 2</td></tr><tr><td>Mura</td><td colspan="2">Not visible through 5% ND filters.</td></tr></table>		Display Area	Total	Note 1	Bright dot	$N \leq 2$	$N \leq 2$	Dark dot	$N \leq 4$	$N \leq 4$	Total dot	$N \leq 4$	$N \leq 4$	Note 2	Mura	Not visible through 5% ND filters.		
				Display Area	Total		Note 1													
Bright dot	$N \leq 2$	$N \leq 2$																		
Dark dot	$N \leq 4$	$N \leq 4$																		
Total dot	$N \leq 4$	$N \leq 4$	Note 2																	
Mura	Not visible through 5% ND filters.																			
		Remark:	1. Bright dot caused by scratch and foreign object accords to item 1.																	

03	Black and White line Scratch Foreign material (Line type) (Minor defect)	 <table border="1"> <thead> <tr> <th>Length</th><th>Width</th><th>Acc. Qty</th></tr> </thead> <tbody> <tr> <td>/</td><td>$W \leq 0.03$</td><td>Ignore</td></tr> <tr> <td>$L \leq 2.5$</td><td>$0.03 < W \leq 0.05$</td><td>3</td></tr> <tr> <td>$L \leq 2.5$</td><td>$0.05 < W \leq 0.10$</td><td>2</td></tr> <tr> <td>/</td><td>$0.1 < W$</td><td>0</td></tr> <tr> <td colspan="2">Total</td><td>3</td></tr> </tbody> </table> Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.	Length	Width	Acc. Qty	/	$W \leq 0.03$	Ignore	$L \leq 2.5$	$0.03 < W \leq 0.05$	3	$L \leq 2.5$	$0.05 < W \leq 0.10$	2	/	$0.1 < W$	0	Total		3
Length	Width	Acc. Qty																		
/	$W \leq 0.03$	Ignore																		
$L \leq 2.5$	$0.03 < W \leq 0.05$	3																		
$L \leq 2.5$	$0.05 < W \leq 0.10$	2																		
/	$0.1 < W$	0																		
Total		3																		
04	Glass Crack (Minor defect)	 Crack is potential to enlarge, any type is not allowed.																		

05	Glass Chipping Pad Area: (Minor defect)								
		<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>3</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	3	$a < \text{Glass Thickness}$
Length and Width	Acc. Qty								
$c > 3.0, b < 1.0$	1								
$c < 3.0, b < 1.0$	3								
$a < \text{Glass Thickness}$									

06	Glass Chipping Rear of Pad Area: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
07	Glass Chipping Except Pad Area: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
08	Glass Corner Chipping: (Minor defect) 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c < 3.0, b < 3.0$</td><td>Ignore</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c < 3.0, b < 3.0$	Ignore	$a < \text{Glass Thickness}$					
Length and Width	Acc. Qty											
$c < 3.0, b < 3.0$	Ignore											
$a < \text{Glass Thickness}$												
09	Glass Burr: (Minor defect) 	<table><tr><th>Length</th><th>Acc. Qty</th></tr><tr><td>$F < 1.0$</td><td>Ignore</td></tr></table> Glass burr don't affect assemble and module dimension.	Length	Acc. Qty	$F < 1.0$	Ignore						
Length	Acc. Qty											
$F < 1.0$	Ignore											

10	FPC Defect: (Minor defect) 	10.1 Dent, pinhole width $a < w/3$. (w: circuitry width.) 10.2 Open circuit is unacceptable. 10.3 No oxidation, contamination and distortion.										
11	Bubble on Polarizer (Minor defect)	<table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$\varphi \leq 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < \varphi \leq 0.30$</td><td>4</td></tr><tr><td>$0.30 < \varphi \leq 0.50$</td><td>1</td></tr><tr><td>$0.50 < \varphi$</td><td>None</td></tr></table>	Diameter	Acc. Qty	$\varphi \leq 0.20$	Ignore	$0.20 < \varphi \leq 0.30$	4	$0.30 < \varphi \leq 0.50$	1	$0.50 < \varphi$	None
Diameter	Acc. Qty											
$\varphi \leq 0.20$	Ignore											
$0.20 < \varphi \leq 0.30$	4											
$0.30 < \varphi \leq 0.50$	1											
$0.50 < \varphi$	None											
12	Dent on Polarizer (Minor defect)	<table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$\varphi \leq 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < \varphi \leq 0.30$</td><td>4</td></tr><tr><td>$0.30 < \varphi \leq 0.50$</td><td>1</td></tr><tr><td>$0.50 < \varphi$</td><td>None</td></tr></table>	Diameter	Acc. Qty	$\varphi \leq 0.20$	Ignore	$0.20 < \varphi \leq 0.30$	4	$0.30 < \varphi \leq 0.50$	1	$0.50 < \varphi$	None
Diameter	Acc. Qty											
$\varphi \leq 0.20$	Ignore											
$0.20 < \varphi \leq 0.30$	4											
$0.30 < \varphi \leq 0.50$	1											
$0.50 < \varphi$	None											
13	Bezel	13.1 No rust, distortion on the Bezel. 13.2 No visible fingerprints, stains or other contamination.										
14	Touch Panel	D: Diameter W: width L: length 14.1 Spot: $D < 0.25$ is acceptable $0.25 \leq D \leq 0.4$ 2dots are acceptable and the distance between defects should more than 10 mm. $D > 0.4$ is unacceptable 14.2 Dent: $D > 0.40$ is unacceptable 14.3 Scratch: $W \leq 0.03$, $L \leq 10$ is acceptable, $0.03 < W \leq 0.10$, $L \leq 10$ is acceptable Distance between 2 defects should more than 10 mm. $W > 0.10$ is unacceptable.										
15	PCB	15.1 No distortion or contamination on PCB terminals. 15.2 All components on PCB must same as documented on the BOM/component layout. 15.3 Follow IPC-A-600F.										
16	Soldering	Follow IPC-A-610C standard										

17	Electrical Defect (Major defect)	The below defects must be rejected. 17.1 Missing vertical / horizontal segment, 17.2 Abnormal Display. 17.3 No function or no display. 17.4 Current exceeds product specifications. 17.5 LCD viewing angle defect. 17.6 No Backlight. 17.7 Dark Backlight. 17.8 Touch Panel no function.
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Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

11.7. Classification of Defects

11.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.

11.7.2. Two minor defects are equal to one major in lot sampling inspection.

11.8. Identification/marketing criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

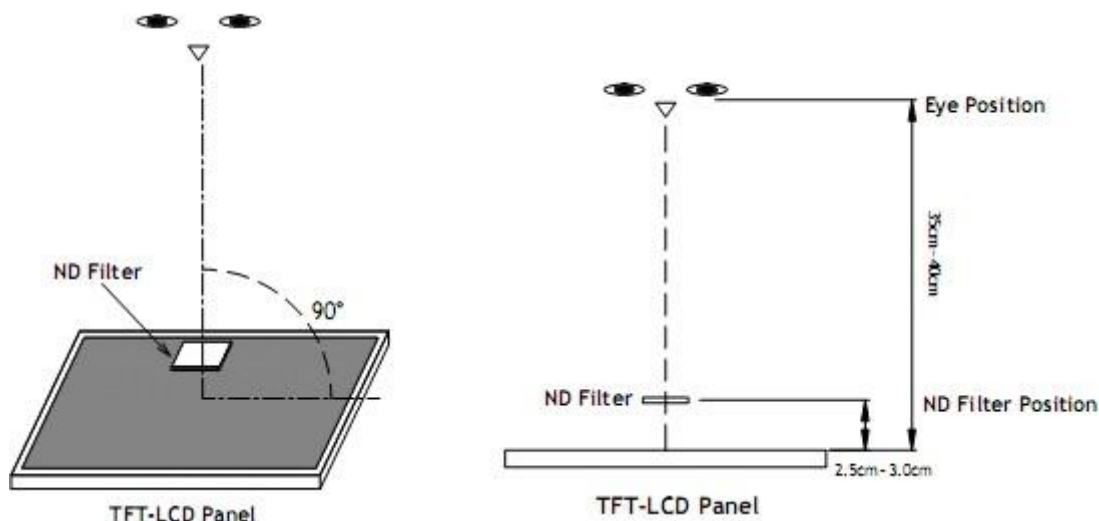
11.9. Packing

11.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.

11.9.2. Modules inside package box should have compliant mark.

11.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350\text{mm} \pm 50\text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is $350\text{mm} \pm 50\text{mm}$.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

12. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	60°C, 96Hrs	2	GB/T2423.2-2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1-2008
3	High Humidity	50°C, 90%RH, 96Hrs	2	GB/T2423.3-2016
4	High Temperature Storage	70°C, 96Hrs	2	GB/T2423.2-2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1-2008
6	Thermal Cycling Test	-20°C, 60min ~ 60°C, 60min, 20 cycles.	2	GB/T2423.22-2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	2	GB/T5170.14-2009
8	Electrical Static Discharge	Air: $\pm 4KV$ 150pF/330 Ω 5 times Contact: $\pm 2KV$ 150pF/330 Ω 5 times	2	GB/T17626.2-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8-1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

13. Precautions and Warranty

13.1. Safety

- 13.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 13.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

13.2. Handling

- 13.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 13.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

13.3. Storage

- 13.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 13.3.2. Strong light exposure causes degradation of polarizer and color filter.

13.4. Metal Pin (Apply to Products with Metal Pins)

13.4.1. Pins of LCD and Backlight

- 13.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

13.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

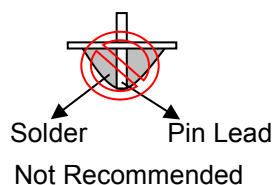
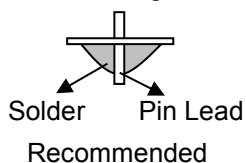
Maximum Solder Temperature: 370℃

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20℃

Typical Soldering Time: ≤3s

13.4.1.3. Solder Wetting



13.4.2. Pins of EL

- 13.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

- 13.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

13.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290℃

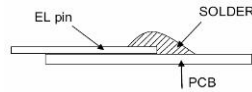
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body): 2.0mm

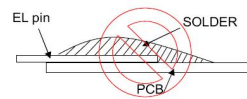
- 13.4.2.4. No horizontal press on the EL leads during soldering.

- 13.4.2.5. 180° bend EL leads three times is not allowed.

13.4.2.6. Solder Wetting

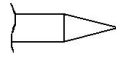


Recommended

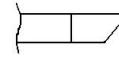


Not Recommended

13.4.2.7. The type of the solder iron:

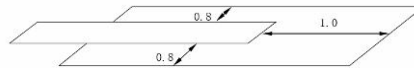


Recommended



Not Recommended

13.4.2.8. Solder Pad



13.5. Operation

- 13.5.1. Do not drive LCD with DC voltage
- 13.5.2. Response time will increase below lower temperature
- 13.5.3. Display may change color with different temperature
- 13.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.
- 13.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 13.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 13.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 13.5.8. *Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.*

13.6. Static Electricity

- 13.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 13.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 13.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

13.7. Limited Warranty

- 13.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 13.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 13.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

14. Packaging

TBD

15. Outline Drawing

